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PATENT, TRADEMARK, COPYRIGHT AND UNFAIR COMPETITION CAUSES

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February 18, 2003

PATENT AND TRADEMARK FACSIMILE COVER SHEET

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper is being facsimile transmitted to the Patent and Trademark Office on the date shown below:

Date: 2-18-03Kristin West
SignatureKristin West
NameTo: Patent and Trademark Office
Att: Examiner Scott B. Geyer
Fax: 1-703-872-9319
No. of pages: 12From: Stetina Brunda Garred & Brucker
Attorney: Mark B. Garred
Reg. No. 34,823
Re: Case No. : AMKOR-048A
Patent Application No. : 09/687,495
Applicant: Sean Timothy Crowley, et al.
Filed: 10/13/2000
Title: SEMICONDUCTOR PACKAGE

PLEASE HAND DELIVER TO: Examiner Scott B. Geyer

Case No.: AMKOR-048A
Patent Appln.

#221D Audit
JHE M. Brunson
2/27/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Sean Timothy Crowley et al.)	
)	
Serial No.:	09/687,495)	Group No.: 2829
)	
Filed:	10/13/2000)	Examiner: Geyer, Scott B.
)	
For:	SEMICONDUCTOR PACKAGE)	

AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. §1.116

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON D.C. 20231

Dear Sir/Madam:

In response to the final Office Action mailed November 19, 2002, in relation to the above-identified patent application, please amend the application as follows:

In the Claims:

Please amend the following claims:

1. (Four Times Amended) A semiconductor package, comprising:
- a semiconductor chip having an upper surface provided with a plurality of input/output pads thereon;
 - a chip paddle adjacent a bottom surface of the semiconductor chip, said chip paddle having an upper surface and a lower surface;
 - a plurality of leads surrounding the chip paddle and having upper and lower surfaces, wherein the chip paddle has a maximum thickness which exceeds a maximum